+3.3V and +5.0V, RS-485 Half-Duplex Transceiver with ±65V Fault Protection, ±40V CMR, and ±40kV ESD

General Description

The MAX33070E/MAX33071E/MAX33074E are a family of fault-protected RS-485/RS-422 transceivers with high ±65V protection for overvoltage conditions on the communication bus lines, ensuring robust protection in harsh industrial environments. All devices have ±40V of common-mode range (CMR) within V_{CCH} (+4.5V to +5.5V), exceeding the RS-485 standard of -7V to +12V, making them suitable for electrically noisy environments where different systems have shifting ground levels relative to each other. They also incorporate a high ESD protection circuit capable of protecting against ±40kV of ESD Human Body Model (HBM) for driver outputs and receiver inputs (A and B data lines). Each device contains one driver and one receiver and operates over the +3V to +5.5V supply range, making it convenient for designers to use one part with either +3.3V or +5V supply voltages across multiple end equipment.

These devices feature a receiver enable ($\overline{\text{RE}}$) input that allows for a low-current shutdown state. The MAX33070E features slew-rate-limited outputs for data rates up to 500kbps. For applications requiring higher bandwidth, the MAX33071E is rated up to 2Mbps, and the MAX33074E up to 20Mbps. These transceivers are optimized for robust communication in noisy environments. A true fail-safe feature guarantees a logic-high on the receiver output when the inputs are open or shorted. Driver outputs are protected against short-circuit conditions. The receivers feature a 1/8-unit load input impedance, allowing up to 256 transceivers on a bus

The MAX33070E/MAX33071E are available in an 8-pin SO, and the MAX33074E is available in an 8-pin SO with an exposed pad. All three devices operate over the -40°C to +125°C temperature range.

Applications

- Industrial Automation Equipment
- Home and Building Automation
- Agriculture and Heavy Machinery
- Power Supply and UPS
- Elevator Control
- Motion Controllers

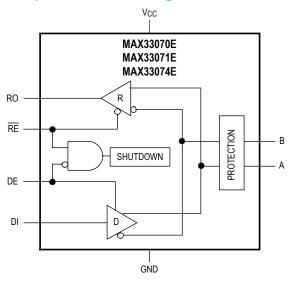
Benefits and Features

- Integrated Protection for Robust Communication
 - Protection on Driver Outputs/Receiver Inputs (A, B Data Lines)
 - ±65V Fault Protection Range on Driver Outputs/Receiver Inputs
 - ±40V Common-Mode Range on Driver Outputs/Receiver Inputs
 - ±40kV Human Body Model (JEDEC JS-001-2017) ESD Protection
 - ±15kV Air-Gap Discharge (IEC 61000-4-2) ESD Protection
 - ±10kV Contact Discharge (IEC 61000-4-2)
 ESD Protection
 - Hot-Swap Protection
 - Short-Circuit Protection
 - Thermal Shutdown
 - True Fail-Safe Guarantees Known Receiver Output State
 - Wide Operating Temperature Range from -40°C to +125°C
- High-Performance Transceiver Enables Flexible Designs
 - · Compliant with RS-485 EIA/TIA-485 Standard
 - 500kbps (MAX33070E), 2Mbps (MAX33071E), 20Mbps (MAX33074E) Maximum Data Rate
 - 3.3V and 5.0V Supply Voltage
 - 1/8 Unit Load for up to 256 Devices on the Bus

Ordering Information appears at end of data sheet.



Simplified Block Diagram



+3.3V and +5.0V, RS-485 Half-Duplex Transceiver with ±65V Fault Protection, ±40V CMR, and ±40kV ESD

Absolute Maximum Ratings

V _{CC}	0.3V to +6V
RO	0.3V to V_{CC} + 0.3V
DE, DI, RE	0.3V to +6V
A, B (Continuous)	70V to +70V
Short-Circuit Duration (RO, A, B)	Continuous
Continuous Power Dissipation	
8-Pin SO +70°C (derate 7.6mW/°C ab	ove +70°C) 606.1mW

 8-Pin SO-EP +70°C (derate 2		
Operating Temperature Range	4	10°C to +125°C
Junction Temperature		+150°C
Storage Temperature Range	6	65°C to +150°C
Lead Temperature (soldering, 10	os)	+300°C
Soldering Temperature (reflow)		+260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Package Information

SO

Package Code	S8+4				
Outline Number	<u>21-0041</u>				
Land Pattern Number	90-0096				
Thermal Resistance, Four-Layer Board					
Junction to Ambient (θ _{JA})	132°C/W				
Junction to Case (θ _{JC})	38°C/W				

SO-EP

Package Code	S8E+14C
Outline Number	<u>21-0111</u>
Land Pattern Number	<u>90-0151</u>
Thermal Resistance, Four-Layer Board	
Junction to Ambient (θ _{JA})	41°C/W
Junction to Case (θ _{JC})	7°C/W

For the latest package outline information and land patterns (footprints), go to www.maximintegrated.com/packages. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to www.maximintegrated.com/thermal-tutorial.

+3.3V and +5.0V, RS-485 Half-Duplex Transceiver with ±65V Fault Protection, ±40V CMR, and ±40kV ESD

Electrical Characteristics

 $(V_{CC} = 3.0V \text{ to } 3.6V \text{ and } V_{CC} = 4.5V \text{ to } 5.5V, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are at } V_{CC} = 5.0V \text{ and } T_A = +25^{\circ}C.$ (Note 1)

+25°C. (Note 1))							
PARAMETER	SYMBOL	CONI	DITIONS	MIN	TYP	MAX	UNITS
POWER				1			
Complex Valtage	Vccl	Low range	Low range			3.6	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
Supply Voltage	Vccн	High range		4.5		5.5	V
Supply Current	lcc	DE = high, RE = I	ow, no load,		6		mA
Shutdown Supply Current	Ishdn	$DE = 0V, \overline{RE} = V_0$	cc		4		μΑ
DRIVER							
Differential Driver		Figure 1a, R _L = 54	4Ω	1.5			
Differential Driver Output	Vod	Figure 1a, R _L = 10	Ω00	2.0			V
		Figure 1b		1.5			
External Common-	V _{СМ}	Figure 1b, Vcc = \	Vccl	-25		+25	V
Mode Voltage	VCM	Figure 1b, Vcc = \	Vссн	-40		+40	V
Change in Magnitude of Differential Driver Output Voltage	ΔV_OD	R_L = 54Ω or 100Ω, Figure 1a (Note 2)		-0.2		+0.2	V
Driver Common- Mode Output Voltage	Voc	$R_L = 54\Omega \text{ or } 100\Omega$	2, Figure 1a	1	Vcc/2	3	V
Change in Magnitude of Common-Mode Voltage	ΔV_{OC}	$R_L = 54\Omega \text{ or } 100\Omega$ (Note 2)), Figure 1a	-0.1		+0.1	V
Single-Ended Driver Output Voltage High	Vон	A or B output, out Isource = 3mA	put is high,	2.4	V _{CC} - 0.2		V
Single-Ended Driver Output Voltage Low	VoL	A or B output, out I _{SINK} = 3mA	put is low,			0.2	V
Driver Short-Circuit Output Current	I _{SC_DR}	$-65V \le (V_A \text{ or } V_B)$ or $V_B) \le +65V (Note: Note: $	< 0V or V _{CC} < (V _A ote 3)			450	mA
Average Driver Short- Circuit Output Current	I _{AVG_SCDR}	$0V \le (V_A \text{ or } V_B) \le V_{CC}$				450	mA
RECEIVER				1			•
Input Current (A, B)	I _A , I _B	$ DE = low, 0V \le V_{CM} = +40V $ $V_{CC} \le 5.5V $ $V_{CM} = -40V $		-424		410	μΑ
Receiver Input Resistance	R _{IN}	Over V _{CM} range		96			kΩ
Common-Mode	V	Vcc = VccL		-25		+25	
Voltage Range	V _{СМ}	$V_{CC} = V_{CCH}$				+40	- V

+3.3V and +5.0V, RS-485 Half-Duplex Transceiver with ±65V Fault Protection, ±40V CMR, and ±40kV ESD

 $(V_{CC} = 3.0 \text{V to } 3.6 \text{V and } V_{CC} = 4.5 \text{V to } 5.5 \text{V}, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are at } V_{CC} = 5.0 \text{V and } T_A = +25 ^{\circ}\text{C}. \text{ (Note 1))}$

PARAMETER	SYMBOL	CONE	DITIONS	MIN	TYP	MAX	UNITS
Receiver Differential Threshold Voltage Rising	V_{TLH}	Over V _{CM} range				-50	mV
Receiver Differential Threshold Voltage Falling	V _{THL}	Over V _{CM} range		-200			mV
Receiver Input Hysteresis	ΔV_{TH}				100		mV
Differential Input Capacitance	C_{A_B}	Measured between	en A and B,		50		pF
LOGIC OUTPUT							1
RO Output Logic- High Voltage	Vон	Isource = 3mA, (V	_A - V _B) ≥ -50mV	V _{CC} - 0.4			V
RO Output Logic-Low Voltage	VoL	I _{SINK} = 3mA, (V _A -	V _B) ≤ -200mV			0.4	V
RO Leakage Current	l _{OZR}	RE = V _{IH} , 0V ≤ V _R	RE = V _{IH} , 0V ≤ V _{RO} ≤ V _{CC}			+1	μΑ
RO Short-Circuit	I I _{OSR} I	$0 \le (V_A - V_B) \le V_{CC} = V_{CCH}$ $V_{CC} = V_{CCH}$		90	90		mA
Current	110581				190		11171
LOGIC INPUTS (DE, D	I, RE)						
Input Logic-High Voltage	VIH			2			V
Input Logic-Low Voltage	V_{IL}					0.8	٧
Input Hysteresis	V _{HYS}				100		mV
Input Leakage Current	l _{IN}	After first transitio	n of DE and RE	-1		+1	μA
Input Impedance on First Transition	R _{IN_FT}	DE		1		10	kΩ
PROTECTION							
Thermal Shutdown Threshold	T _{SHDN}	Temperature risin	g		+160		°C
Thermal Shutdown Hysteresis	T _{HYST}				12		°C
ESD Protection (A, B		Human Body Mod 2017)	Human Body Model (JEDEC JS-001-2017)		±40		
Pins to GND)		IEC 61000-4-2 Contact Discharge			±10		kV
		IEC 61000-4-2 Air	r Gap		±15		1
ESD Protection (All		Human Body Mod	lel		±4000		V
Other Pins)		Charge Device M	odel	±2000]	

+3.3V and +5.0V, RS-485 Half-Duplex Transceiver with ±65V Fault Protection, ±40V CMR, and ±40kV ESD

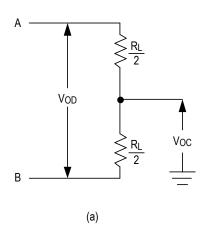
 $(V_{CC} = 3.0 \text{V to } 3.6 \text{V and } V_{CC} = 4.5 \text{V to } 5.5 \text{V}, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are at } V_{CC} = 5.0 \text{V and } T_A = +25 ^{\circ}\text{C}. \text{ (Note 1))}$

PARAMETER	SYMBOL	CONE	DITIONS	MIN	TYP	MAX	UNITS
Fault Protection		A, B independent	y or simultaneously	-65		+65	
Range (A, B Pins to GND)		A and B opposite polarity from separate supplies simultaneously		-65		+65	V
SWITCHING	1						•
DRIVER (Note 4) (Note	e 5)						
Driver Propagation		$R_L = 54\Omega, C_L =$	MAX33070E		50	1000	
Delay	toplh, tophl	50pF (Figure 2) (Figure 3)	MAX33071E/74E		25	50	ns
Differential Driver		$R_L = 54\Omega$, $C_L =$	MAX33070E		10	140	
Output Skew tpplн - tpphl	t dskew	50pF (Figure 2) (Figure 3)	MAX33071E/74E		2	10	ns
Driver Differential		$R_L = 54\Omega$, $C_L =$	MAX33070E		30	600	
Output Rise or Fall Time	t _{LH} , t _{HL}	50pF (Figure 2) (Figure 3)	MAX33071E/74E		8	15	ns
		D 540 0	MAX33070E	0.5			
Maximum Data Rate	DR _{MAX}	$R_L = 54\Omega$, $C_L = 50$ pF	MAX33071E	2			Mbps
		ООР	MAX33074E	20			-
Driver Enable to		$R_L = 110\Omega, C_L =$	MAX33070E		500		
Output High or Output Low	t _{DZH} , t _{DZL}	50pF (Figure 4) (Figure 5)	MAX33071E/74E		400	n	ns
Driver Enable Time	t _D	-40V ≤ V _{CM} ≤	MAX33070E		3.5		μs
Dilver Lilable Time	LD.	+40V, Figure 1b	MAX33071E/74E		1		μο
Driver Disable Time from Output Low or Output High	t _{DLZ} , t _{DHZ}	$R_L = 110\Omega, C_L = 5$ (Figure 5)	i0pF (Figure 4)		500		ns
Driver Enable Time from Shutdown to Output High	t _{DZH_SHDN}	$R_L = 110\Omega$, $C_L = 5$ (Figure 6)	iOpF (Figure 4)		170		μs
Driver Enable Time from Shutdown to Output Low	t _{DZL_} SHDN	$R_L = 110\Omega$, $C_L = 50pF$ (Figure 4) (Figure 6)			170		μs
Time to Shutdown	tshon	(Note 6)		50	800		ns
RECEIVER (Note 4) (N	lote 5)	I .	l				1
Receiver Propagation		$C_L = 15pF$ MAX33070E 1	MAX33070E		130	200	
Delay	t _{RPLH} , t _{RPHL}		55	75	ns		
Receiver Output		C _L = 15pF	MAX33070E		2	30	
Skew	trskew	(Figure 6) (Figure 7)	MAX33071E/74E		1	10	ns

 $(V_{CC} = 3.0 \text{V to } 3.6 \text{V and } V_{CC} = 4.5 \text{V to } 5.5 \text{V}, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are at } V_{CC} = 5.0 \text{V and } T_A = +25 ^{\circ}\text{C}. \text{ (Note 1))}$

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Receiver Enable to Output High	t _{RZH}	R_L = 1k Ω , C_L = 15pF, DE = V _{IH} (Figure 8)		400		ns
Receiver Enable to Output Low	t _{RZL}	R_L = 1k Ω , C_L = 15pF, DE = V _{IH} (Figure 8)		400		ns
Receiver Disable Time from Low	t _{RLZ}	R_L = 1k Ω , C_L = 15pF, DE = V _{IH} (Figure 8)		400		ns
Receiver Disable Time from High	t _{RHZ}	R_L = 1k Ω , C_L = 15pF, DE = V _{IH} (Figure 8)		400		ns
Receiver Enable from Shutdown to Output High	trlz_shdn	$R_L = 1k\Omega$, $C_L = 15pF$ (Figure 8)			170	μs
Receiver Enable from Shutdown to Output Low	trhz_shdn	$R_L = 1k\Omega$, $C_L = 15pF$ (Figure 8)			170	μs
Time to Shutdown	t _{DSHDN}	(Note 6)	50		800	ns

- Note 1: All devices are 100% production tested at $T_A = +25$ °C. Specifications over temperature are guaranteed by design.
- Note 2: ΔV_{OD} and ΔV_{OC} are the changes in V_{OD} and V_{OC} , respectively, when DI changes state.
- Note 3: The short-circuit current is 450mA (max) for a short period (30µs, typ). If the short circuit persists, the outputs are then set to high impedance for 300ms (typ).
- Note 4: Capacitive load includes test probe and fixture capacitance.
- Note 5: Guaranteed by design. Not production tested.
- **Note 6:** Shutdown is enabled when RE is high and DE is low. If the enable inputs are in this state for less than 50ns, the device is guaranteed not to enter shutdown. If the enable inputs are held in this state for at least 800ns, the device is guaranteed to have entered shutdown.



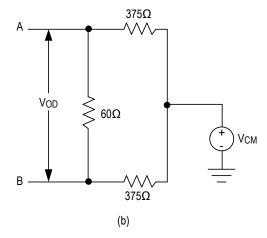


Figure 1. Driver DC Test Load

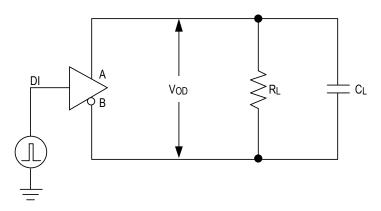


Figure 2. Driver Timer Test Circuit

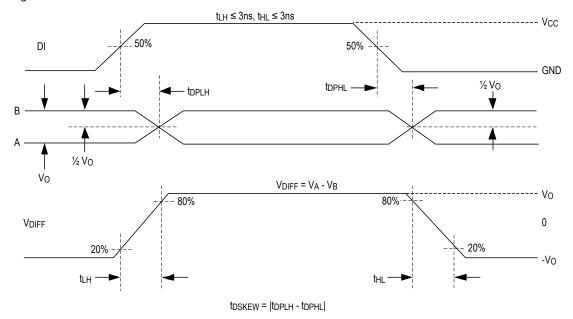


Figure 3. Driver Propagation Delays

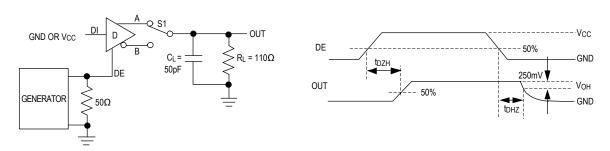


Figure 4. Driver Enable and Disable Times (t_{DHZ} , t_{DZH})

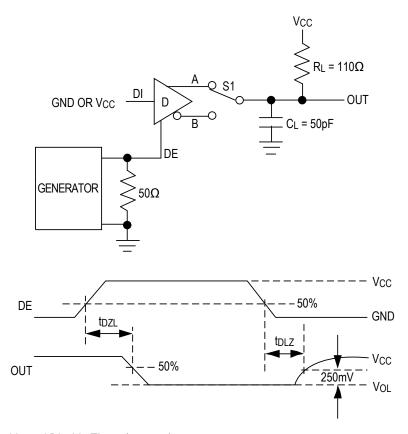


Figure 5. Driver Enable and Disable Times (t_{DZL} , t_{DLZ})

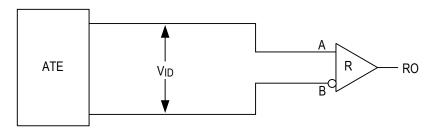


Figure 6. Receiver Propagation Delay Test Circuit

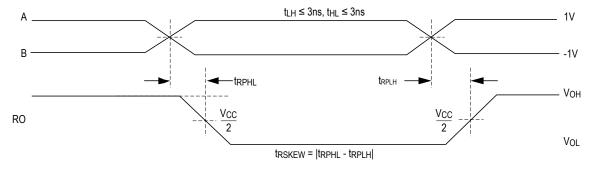


Figure 7. Receiver Propagation Delays

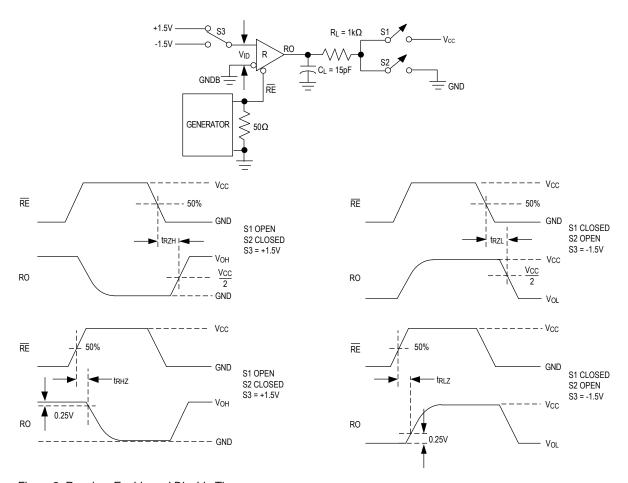
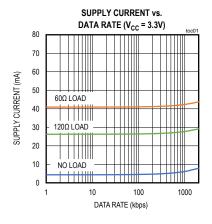
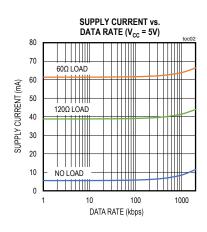


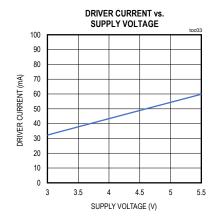
Figure 8. Receiver Enable and Disable Times

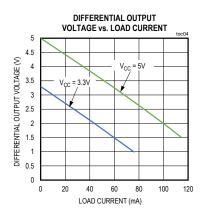
Typical Operating Characteristics

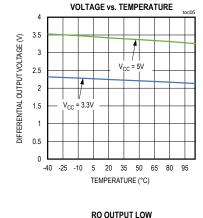
($V_{CC} = 5V$, $T_A = +25$ °C, unless otherwise noted.)



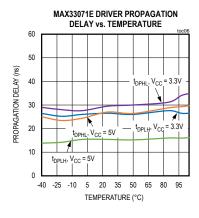


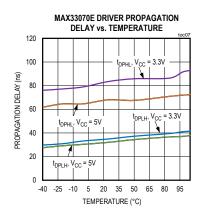


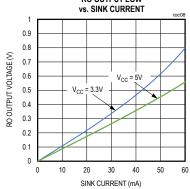


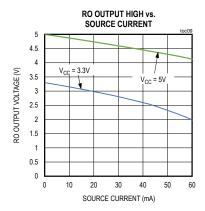


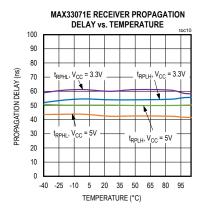
DRIVER DIFFERENTIAL OUTPUT

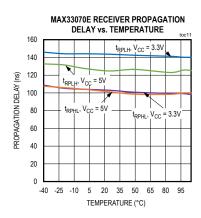


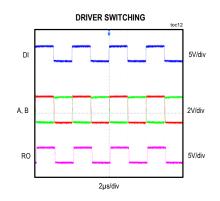




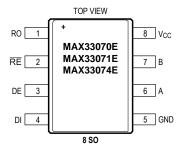








Pin Configuration



Pin Descriptions

PIN	NAME	FUNCTION
1	RO	Receiver Data Output. See the Receiver Truth Table for more information.
2	RE	Receiver Output Enable. Drive \overline{RE} low or connect to GND to enable RO. Drive \overline{RE} high to disable the receiver. RO is high impedance when \overline{RE} is high. Drive \overline{RE} high and DE low to force the IC into low-power shutdown mode.
3	DE	Driver Output Enable. Drive DE high to enable the driver. Drive DE low or connect to GND to disable the driver. Receiver is always enabled.
4	DI	Driver Input. See the Transmitter Truth Table for more information.
5	GND	Ground
6	Α	Noninverting Driver Output/Receiver Input.
7	В	Inverting Driver Output/Receiver Input.
8	Vcc	Power Supply Input. Bypass V_{CC} to GND with a $0.1\mu\text{F}$ capacitor as close as possible to the device.

Detailed Description

The MAX33070E/MAX33071E/MAX33074E half-duplex transceivers are optimized for RS-485/RS-422 applications that require ±65V protection from faults on communication bus lines. These devices contain one differential driver and one differential receiver. These devices feature a 1/8 unit load, allowing up to 256 transceivers on a single bus. The MAX33070E supports a data rate up to 500kbps, the MAX33071E up to 2Mbps, and the MAX33074E up to 20 Mbps.

Driver

The driver accepts a single-ended, logic-level input (DI) and transfers it to a differential RS-485 level output on the A and B driver outputs. Set the driver enable input (DE) low to disable the driver. A and B are high impedance when the driver is disabled.

Table 1. Transmitter Truth Table

RE	DE	DI	Α	В
Х	1	0	0	1
Х	1	1	1	0
0	0	Х	High-Z	High-Z
1	0	Х	High-Z	High-Z

Receiver

The receiver accepts a differential, RS-485 level on the A and B inputs and transfers it to a single-ended, logic-level output (RO). Drive the receiver enable input (\overline{RE}) low to enable the receiver. Drive \overline{RE} logic high to disable the receiver. RO is high impedance when \overline{RE} is logic high.

Table 2. Receiver Truth Table

RE	DE	(V _A - V _B)	RO
0	Х	≥ -50mV	1
0	Х	≤ -200mV	0
0	Х	Open/shorted	1
1	1	Х	High-Z
1	0	Х	High-Z and shutdown

Low-Power Shutdown

Drive DE low and $\overline{\text{RE}}$ high for at least 800ns to put the MAX33070E/MAX33071E/MAX33074E into low-power shutdown mode. The supply current reduces to 4µA when the device is in shutdown mode. A glitch-protection feature ensures this family of transceivers will not accidentally enter shutdown mode due to logic skews between DE and $\overline{\text{RE}}$ when switching between transmit and receive modes.

±65V Fault Protection

The driver outputs/receiver inputs of transceivers connected to an industrial RS-485 network often experience faults when shorted to voltages that exceed the -7V to +12V input range specified in the EIA/TIA-485 standard. Under such circumstances, ordinary RS-485 transceivers that have a typical absolute maximum voltage rating of -8V to +12.5V require costly external protection devices which can compromise the RS-485 performance. To reduce system complexity and the need for external protection, the driver outputs/receiver inputs of the MAX33070E/MAX33071E/MAX33074E are designed to withstand voltage faults of up to ±65V with respect to ground without damage. Protection is guaranteed regardless whether the transceiver is active, in shutdown, or without power. When a fault is detected on A or B, the affected driver

+3.3V and +5.0V, RS-485 Half-Duplex Transceiver with ±65V Fault Protection, ±40V CMR, and ±40kV ESD

output is switched into a high-impedance state. After 300ms (typ), the driver output is re-enabled for 30µs (typ). If the fault condition persists, the driver output is again disabled. If the fault has been removed, the driver outputs remain on and the transceiver operates normally. Driving a non-terminated cable may cause the voltage seen at the driver outputs (A or B) to exceed the absolute maximum voltage rating if the DI input is switched during a ±65V fault on the A or B pins. Therefore, a termination resistor is recommended in order to maximize the overvoltage fault protection while the DI input is being switched. If the DI input does not change state while the fault condition is present, the MAX33070E/MAX33071E/MAX33074E will withstand up to ±65V on the RS-485 inputs, regardless of the termination status of the data cable.

±40V Common-Mode Range

RS-485 standards define the common-mode range as -7V to +12V for the receiver. For this family of transceivers, the common-mode range exceeds the standard with ±40V for both the driver and receiver. This feature was specifically designed for systems where there is a large common-mode voltage present due to either nearby electrically noisy equipment or large ground differences due to different earth grounds or different power transformers. Two-way communication is possible with ±40V high common-mode range where other standard RS-485 transceivers would either fail, not transmit or receive, and/or cause data errors.

True Fail-Safe

The MAX33070E/MAX33071E/MAX33074E guarantees a logic-high receiver output when the receiver inputs are shorted or open, or when they are connected to a terminated transmission line with all drivers disabled. If the differential receiver input voltage ($V_A - V_B$) is greater than or equal to -50mV, RO is logic-high when \overline{RE} is logic-low.

Hot-Swap Inputs

Inserting circuit boards into a hot, or powered backplane may cause voltage transients on DE, and receiver inputs A and B, that can lead to data errors. For example, upon initial circuit board insertion, the processor undergoes a power-up sequence. During this period, the high impedance state of the output drivers makes them unable to drive the MAX33070E/MAX33071E/MAX33074E DE input to a defined logic level. Meanwhile, leakage currents of up to $10\mu A$ from the high-impedance output, or capacitively coupled noise from V_{CC} or GND, could cause an input to drift to an incorrect logic state. To prevent such a condition from occurring, the MAX33070E/MAX33071E/MAX33074E features hot-swap input circuitry on DE to safeguard against unwanted driver activation during hot-swap situations. When V_{CC} rises, an internal pulldown circuit holds DE low for at least $10\mu s$. After the first transition on DE, the internal pulldown/pullup circuitry becomes transparent, resetting the hot-swap tolerable inputs.

Thermal-Shutdown Protection

The MAX33070E/MAX33071E/MAX33074E feature thermal-shutdown protection circuitry to protect the device. When the internal silicon junction temperature exceeds +160°C (typ), the driver outputs are disabled and RO is high impedance. Driver and receiver outputs are re-enabled when the junction temperature falls below +148°C (typ).

Applications Information

256 Transceivers on the Bus

The MAX33070E/MAX33071E/MAX33074E transceivers have 1/8 unit load receiver, allowing for up to 256 transceivers connected in parallel on a shared communication line. Connect any combination of these devices, and/or other RS-485 devices, for a maximum of 32 unit loads on the line.

Typical Application

The MAX33070E/MAX33071E/MAX33074E half-duplex transceivers are designed for bidirectional data communications on multipoint bus transmission lines. The *Typical Application Circuit* shows a typical network application's circuit. To minimize reflections, the bus should be terminated at the receiver inputs in its characteristic impedance, and stub lengths off the main line should be kept as short as possible.

Power Considerations for the MAX33070E/MAX33071E/MAX33074E

At high data rates, the power dissipation of a half-duplex transceiver is determined by a number of factors, including the:

- Data rate
- Time that the driver is transmitting
- Termination impedance
- Power supply voltage
- External common-mode voltage

Higher data rates result in higher power dissipation due to switching losses in the transceiver. Switching losses increase even more when capacitance is applied to the A and B pins. External capacitance should be kept to a minimum to help reduce power dissipations at high data rates. Similarly, the power dissipation in a transceiver is much higher when the driver is transmitting, compared to when the transceiver is receiving. In half-duplex communication, the period of transmission relative to the idle or receiving intervals (i.e., the duty cycle) should be taken into consideration when calculating the average power dissipation. The line termination resistance/impedance determines the driver's load current during transmission and the differential output voltage ($V_{\rm OD}$) on the driver is determined by the supply voltage. A higher supply voltage results in a larger differential output voltage at the driver driving the line, which in turn results in a higher current draw from the supply ($I_{\rm CC}$). The power dissipation in the chip is calculated as the product of supply current times supply voltage, subtracting the power dissipated in the external termination resistor. If there is a common-mode voltage (higher than $V_{\rm CC}$) present (Figure 1b), the transceiver will pull this voltage down to operating levels by sinking current into the A pin (or B pin, whichever is lower). This is factored into the following equation:

$$P_{DIS} = (V_{CC} \times I_{CC}) - (V_{OD}^2/R_L) + (V_{AB} \times I_{AB})$$

where
$$I_{AB} = ((V_{CM} - V_{AB})/375) + ((V_{CC}-V_{AB})/R_L)$$
.

Use the *Typical Operating Characteristics* to determine the supply current at a given supply voltage and data rate. For example, assuming a data rate of 500kbps with a 5V supply on a fully loaded bus with +40V common mode (Figure 1b), and assuming $V_{AB} = 1.5V$ (the lower of A, B), we can calculate that the power dissipation (at room temperature) is:

$$P_{DIS} = (5V \times 65 \text{mA}) - (3.4V^2/60\Omega) + (1.5V \times 160 \text{mA}) = 564 \text{mW}$$

Ensure that power dissipation of the transceiver is kept below the value listed in the *Absolute Maximum Ratings* to protect the device from entering thermal shutdown or from damage.

PCB Layout Considerations

PCB layout can affect the performance of the transceiver in conditions with high common-mode voltage at a high ambient temperature. In order to maximize thermal dissipation, it is recommended to:

- 1. Use large copper pads for all the pins.
- 2. Connect the GND pad to a large copper plane on the same layer or through vias to the bottom layer.

ESD Protection

ESD protection structures are incorporated on all pins to protect against electrostatic discharge encountered during handling and assembly. The driver outputs and receiver inputs (A and B data lines) of the MAX33070E/MAX33071E/MAX33074E have extra protection against static electricity. The ESD structures withstand high ESD in normal operation and when powered down. After an ESD event, the devices keep working without latch-up or damage.

ESD protection can be tested in various ways. The transmitter outputs and receiver inputs (A and B data lines) of the devices are characterized for protection to the cable-side ground (GNDB) to the following limits:

- ±40kV HBM per JEDEC JS-001-2017
- ±15kV using the Air-Gap Discharge method specified in the IEC 61000-4-2
- ±10kV using the Contact Discharge method specified in the IEC 61000-4-2

The other non-data pins are also ESD protected, but at a lower level per the Electrical Characteristics table.

ESD Test Conditions

ESD performance depends on a variety of conditions. Contact Maxim for a reliability report that documents test setup, test methodology, and test results.

Human Body Model (HBM)

Figure 9 shows the HBM test model and Figure 10 shows the current waveform it generates when discharged in a low-impedance state. This model consists of a 100pF capacitor charged to the ESD voltage of interest, which is then discharged into the test device through a 1.5kΩ resistor.

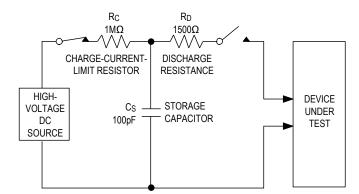


Figure 9. Human Body ESD Test Model

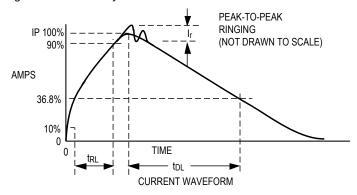


Figure 10. Human Body Current Waveform

IEC 61000-4-2

The IEC 61000-4-2 standard covers ESD testing and performance of finished equipment. However, it does not specifically refer to integrated circuits. The MAX33070E/MAX33071E/MAX33074E help in designing equipment to meet IEC 61000-4-2 without the need for additional ESD protection components. The major difference between tests done using the HBM and IEC 61000-4-2 is higher peak current in IEC 61000-4-2 because series resistance is lower in the IEC 61000-4-2 model. Hence, the ESD withstand voltage measured to IEC 61000-4-2 is generally lower than that measured using the HBM. **Figure 11** shows the IEC 61000-4-2 model and **Figure 12** shows the current waveform for IEC 61000-4-2 ESD Contact Discharge, and Air-Gap tests.

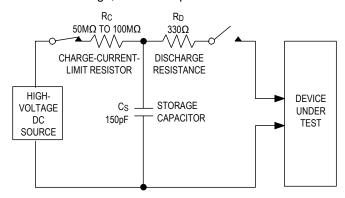


Figure 11. IEC 61000-4-2 ESD Test Model

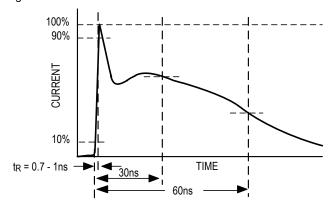
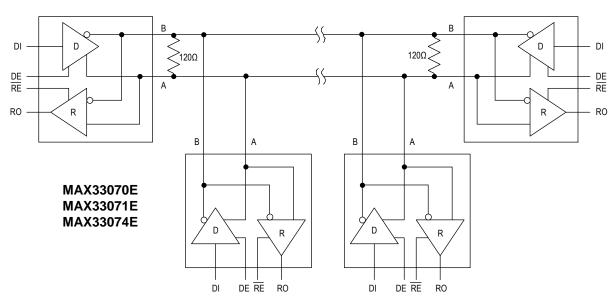


Figure 12. IEC 61000-4-2 ESD Generator Current Waveform

Typical Application Circuits

Typical RS-485 Network



Ordering Information

PART NUMBER	TEMPERATURE RANGE	PIN-PACKAGE	MAXIMUM DATA RATE
MAX33070EASA+	-40°C to +125°C	8 SO	500kbps
MAX33070EASA+T	-40°C to +125°C	8 SO	500kbps
MAX33071EASA+	-40°C to +125°C	8 SO	2Mbps
MAX33071EASA+T	-40°C to +125°C	8 SO	2Mbps
MAX33074EASA+*	-40°C to +125°C	8 SO-EP	20Mbps
MAX33074EASA+T*	-40°C to +125°C	8 SO-EP	20Mbps

^{+ =} Denotes a lead(Pb)-free/RoHS-compliant package.

T = Tape and reel.

^{*}Future product—contact factory for availability.

+3.3V and +5.0V, RS-485 Half-Duplex Transceiver with ±65V Fault Protection, ±40V CMR, and ±40kV ESD

Revision History

REVISION	REVISION	DESCRIPTION	PAGES
NUMBER	DATE		CHANGED
0	1/21	Initial release	_

For pricing, delivery, and ordering information, please visit Maxim Integrated's online storefront at https://www.maximintegrated.com/en/storefront/storefront.html.

Maxim Integrated cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim Integrated product. No circuit patent licenses are implied. Maxim Integrated reserves the right to change the circuitry and specifications without notice at any time. The parametric values (min and max limits) shown in the Electrical Characteristics table are guaranteed. Other parametric values quoted in this data sheet are provided for guidance.